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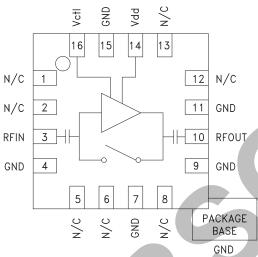
GaAs PHEMT MMIC LOW NOISE AMPLIFIER w/ BYPASS MODE, 4.8 - 6.0 GHz

Typical Applications

The HMC604LP3 / HMC604LP3E is ideal for:

- · WiMAX/C-band Radio
- Fixed Wireless
- Tower Mounted Amplifiers
- · Public Safety Infrastructure
- · Telematics & DSRC

Functional Diagram



Features

Noise Figure: 1.5 dB Output IP3: +26 dBm

Gain: 15 dB

Integrated Low Loss LNA Bypass Path

Single Supply: +3V or +5V

50 Ohm Matched Output/Input

16 Lead 3x3mm QFN Package: 9 mm²

General Description

The HMC604LP3(E) is a versatile, high dynamic range GaAs MMIC Low Noise Amplifier that integrates a low loss LNA bypass mode on the IC. The amplifier is ideal for WiMAX & C-band Radio receivers operating between 4.8 and 6.0 GHz and provides 1.5 dB noise figure, 15 dB of gain and +26 dBm IP3 from a single supply of +5V @ 42mA. Input and output return losses are 12 and 14 dB respectively with no external matching components required. A single control line (0/Vdd) is used to switch between LNA mode and a low loss bypass mode which reduces the current consumption to 10 µA.

Electrical Specifications, $T_A = +25^{\circ}$ C

| | | | Vdd = | = +3V | | | | | Vdd = | +5V | | | |
|---|------|---------|-------|-------|---------|------|------|--------|-------|-------|---------|------|-------|
| Parameter | l | _NA Mod | le | Ву | pass Mo | ode | L | NA Mod | le | Ву | pass Mo | ode | Units |
| | Min. | Тур. | Max. | Min. | Тур. | Max. | Min. | Тур. | Max. | Min. | Тур. | Max. | Units |
| Frequency Range | | | 4.8 | - 6.0 | | | | | 4.8 | - 6.0 | | | GHz |
| Gain | 10 | 12.5 | | -3 | -2 | | 13 | 15 | | -3 | -2 | | dB |
| Gain Variation Over Temperature | | 0.026 | | | 0.002 | | | 0.026 | | | 0.002 | | dB/°C |
| Noise Figure | | 1.6 | 2.1 | | 2 | | | 1.5 | 2 | | 2 | | dB |
| Input Return Loss | | 14 | | | 20 | | | 12 | | | 20 | | dB |
| Output Return Loss | | 15 | | | 20 | | | 14 | | | 20 | | dB |
| Reverse Isolation | | 28 | | | - | | | 30 | | | - | | dB |
| Power for 1dB Compression (P1dB)* | | 10 | | | 24 | | | 14 | | | 24 | | dBm |
| Saturated Output Power (Psat) | | 10.5 | | | 25 | | | 14.5 | | | 25 | | dBm |
| Third Order Intercept (IP3)* (-20 dBm Input Power per tone, 1 MHz tone spacing) | | 21 | | | 23 | | | 26 | | | 23 | | dBm |
| Supply Current (Idd) | | 17 | 25 | | 0.01 | | | 42 | 55 | | 0.01 | | mA |
| Switching LNA Mode to Bypass Mode | | 7 | | | | | | 6 | | | | | ns |
| Speed Bypass Mode to LNA Mode | | | | | 50 | | | | | | 150 | | ns |

^{*} P1dB and IP3 for LNA Mode are referenced to RFOUT while P1dB for Bypass Mode is referenced to RFIN.

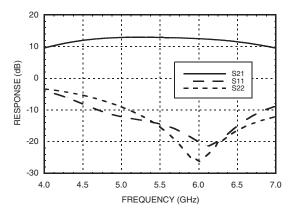


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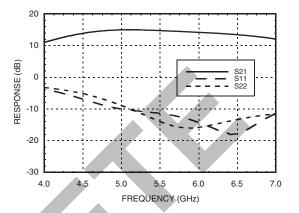


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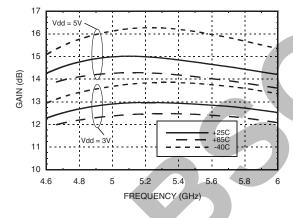
LNA Broadband Gain & Return Loss @ Vdd= 3V



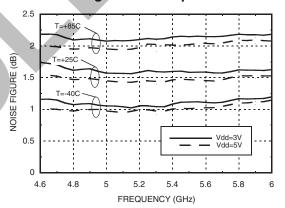
LNA Broadband Gain & Return Loss @ Vdd= 5V



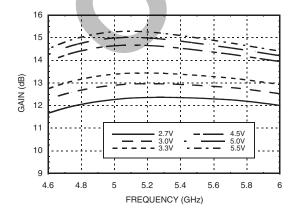
LNA Gain vs. Temperature



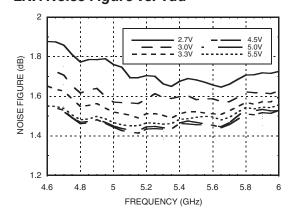
LNA Noise Figure vs. Temperature



LNA Gain vs. Vdd



LNA Noise Figure vs. Vdd



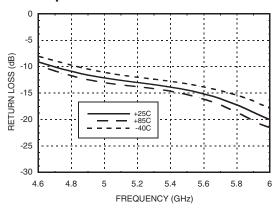


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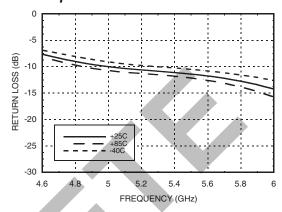
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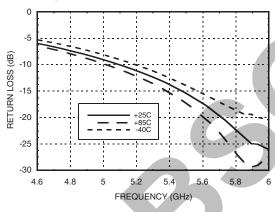
LNA Input Return Loss vs. Temperature @ Vdd= 3V



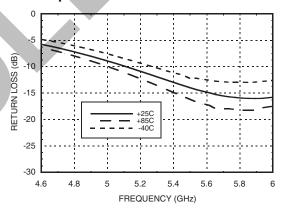
LNA Input Return Loss vs. Temperature @ Vdd= 5V



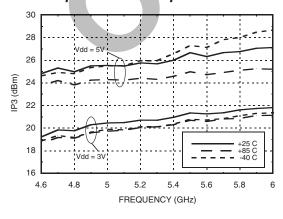
LNA Output Return Loss vs. Temperature @ Vdd= 3V



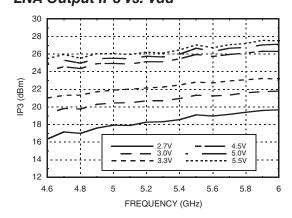
LNA Output Return Loss vs. Temperature @ Vdd= 5V



LNA Output IP3 vs. Temperature



LNA Output IP3 vs. Vdd



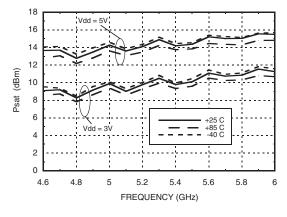


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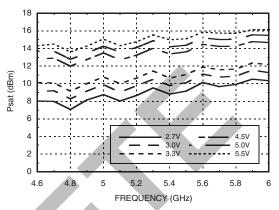


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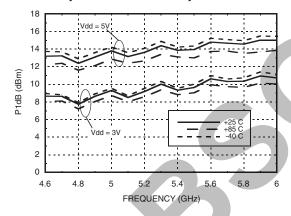
LNA Psat vs. Temperature



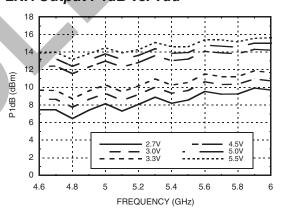
LNA Psat vs. Vdd



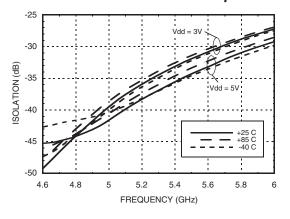
LNA Output P1dB vs. Temperature



LNA Output P1dB vs. Vdd



LNA Reverse Isolation vs. Temperature



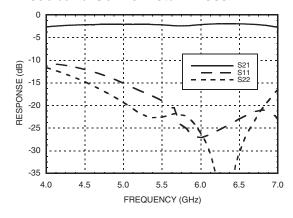


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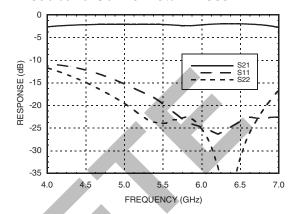


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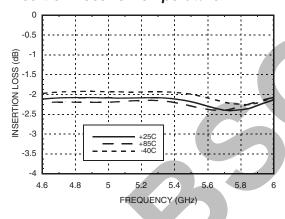
Bypass Mode
Broadband Gain & Return Loss [1]



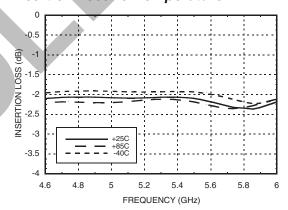
Bypass Mode Broadband Gain & Return Loss [2]



Bypass Mode Insertion Loss vs. Temperature [1]



Bypass Mode Insertion Loss vs. Temperature [2]



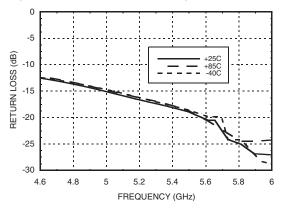


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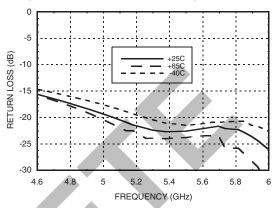


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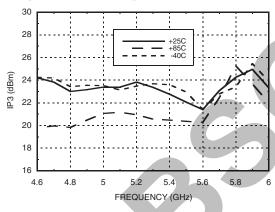
Bypass Mode Input Return Loss vs. Temperature [1]



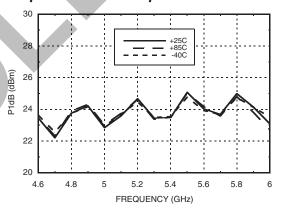
Bypass Mode Output Return Loss vs. Temperature [1]



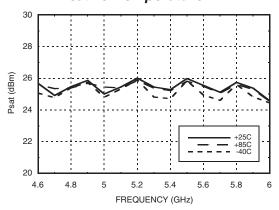
Bypass Mode Output IP3 vs. Temperature [1]



Bypass Mode
Output P1dB vs. Temperature [1]



Bypass Mode Psat vs. Temperature [1]



[1] Vdd = 3V or Vdd = 5V



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GaAs PHEMT MMIC LOW NOISE AMPLIFIER w/ BYPASS MODE, 4.8 - 6.0 GHz

Absolute Maximum Ratings

| Drain Bias Voltage (Vdd) | +8 Vdc |
|---|--------------------|
| RF Input Power (RFIN) LNA Mode (Vdd = +5.0 Vdc) Bypass Mode | +15 dBm +30 dBm |
| Channel Temperature | 150 °C |
| Continuous Pdiss (T = 85 °C) (derate 13 mW/°C above 85 °C) | 850 mW |
| Thermal Resistance (channel to ground paddle) | 76.9 °C/W |
| Storage Temperature | -65 to +150° C |
| Operating Temperature | -40 to +85° C |

ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

Typical Supply Current vs. Vdd

| Vdd (Vdc) | ldd (mA) |
|-----------|----------|
| +2.7 | 13 |
| +3.0 | 17 |
| +3.3 | 21 |
| +4.5 | 37 |
| +5.0 | 42 |
| +5.5 | 46 |

Truth Table

| LNA Mode | Vctl= Vdd |
|-------------|-----------|
| Bypass Mode | Vctl= 0V |

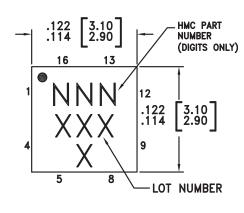


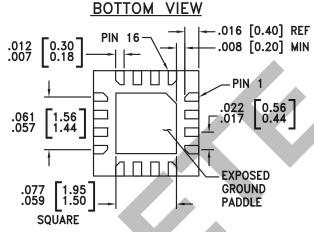


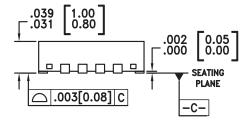


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Outline Drawing







NOTES:

- 1. LEADFRAME MATERIAL; COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
- PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

| Part Number | Package Body Mate | rial Lead Finish | MSL Rating | Package Marking [3] |
|-------------|-----------------------------------|----------------------------------|------------|---------------------|
| HMC604LP3 | Low Stress Injection Molde | ed Plastic Sn/Pb Solder | MSL1 [1] | 604 XXXX |
| HMC604LP3E | RoHS-compliant Low Stress Injecti | ion Molded Plastic 100% matte Sn | MSL1 [2] | 604 XXXX |

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX



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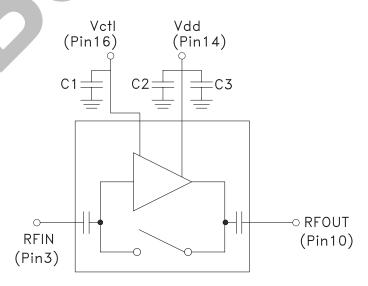
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Pin Descriptions

| Pin Number | Function | Description | Interface Schematic |
|----------------------|----------|--|---------------------|
| 1, 2, 5, 6, 8, 12 | N/C | No connection necessary. These pins may be connected to RF/DC ground. | |
| 3 | RFIN | This pin is AC coupled and matched to 50 Ohms. | RFIN ○── |
| 4, 7, 9, 11, 15 | GND | These pins must be connected to RF/DC ground. | ○ GND = |
| 10 | RFOUT | This pin is AC coupled and matched to 50 Ohms. | RFOUT |
| 14 | Vdd | Power supply voltage. Bypass capacitors are required. See application circuit. | Vdd |
| 16 | Vctl | LNA/Bypass Mode Control Voltage. See truth table. | Vetlo |

Application Circuit

| Components | Value |
|------------|-------|
| C1, C2 | 100pF |
| СЗ | 10KpF |



ANALOGDEVICES

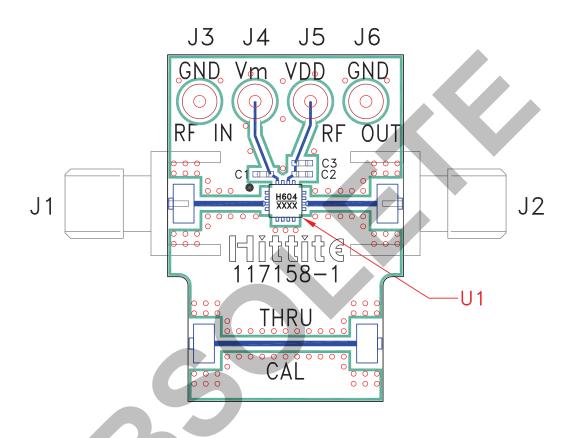
HMC604LP3 / 604LP3E

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Evaluation PCB



List of Materials for Evaluation PCB 117160 [1]

| Item | | Description | | |
|---------|---|----------------------------------|--|--|
| J1 - J2 | | PCB Mount SMA RF Connector | | |
| J3 - J6 | _ | DC Pin | | |
| C1, C2 | | 100 pF Capacitor, 0402 Pkg. | | |
| C3 | | 10 KpF Capacitor, 0402 Pkg. | | |
| U1 | | HMC604LP3 / HMC604LP3E Amplifier | | |
| PCB [2] | | 117158 Evaluation Board | | |

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350